AMENDMENTS TO THE CLAIMS

1. (Currently Amended) An online entrusting system for a semiconductor package comprises:

a ~~processing controller~~manage and control unit to process ~~an~~ semiconductor package order inputted by a user via an interface of internet, wherein said order includes a required~~requiring~~ information selected from at least one information of a substrate, a die dimension, a package type, a thermal performance, an amount of substrate layers, numbers of input terminals and output terminals, and pitches between said input and output terminals about said semiconductor package;

a database coupled to said ~~processing controller~~manage and control unit to store said required~~requiring~~ information and a schedule information;

a plurality of analysis~~analyzing~~ modules coupled to said ~~processing controller~~manage and control unit to produce an analysis result about said required~~requiring~~ information ~~being attained or not~~; and

a reply~~ing~~ means responding said analysis result of said analysis~~analyzing~~ modules to said user.

2-9. (Cancelled)

10. (Currently Amended) The system of claim 1, wherein said schedule information includes a~~the~~ progress information about processing said order and a~~the~~ result for processing said order.

11. (Currently Amended) The system of claim 1, wherein said plurality of analysis~~analyzing~~ modules are selected from at least one of ~~include~~ a~~the~~ thermal analysis module, a circuit analysis module, a stress analysis module, a reliability analysis module, a material analysis module and a substrate analysis module.

12. (Currently Amended) A method for automatically providing online package entrusting comprises:

inputting ~~an~~ required~~requiring~~ information about a semiconductor package by a user via an internet, wherein said required information is selected from at least one information of a substrate, a die dimension, a package type, a thermal performance, an amount of substrate layers, numbers of input terminals and output terminals, and pitches between said input and output terminals about said semiconductor package;

storing said required~~requiring~~ information in a database;

producing a plurality of analysis results by a plurality of analysis modules according to said required~~requiring~~ information of said order;

recording said analysis results in said database; and

responding said analysis results to said user by a reply~~replying~~ means.

13-19. (Cancelled)

20. (Currently Amended) The method of claim 12, wherein said plurality of analysis~~analyzing~~ modules are selected from at least one of ~~include~~ a~~the~~ thermal analysis

module, a circuit analysis module, a stress analysis module, a reliability analysis module, a

material analysis module and a substrate analysis module.